

08-19-2008

COMMERCE  
Remark Office

RECORDATION FOR  
PATENTS



103520468

s) below.

To the Director of the U.S. Patent and Trademark Office: Please

1. Name of conveying party(ies):

Ke-Chih Chang (07/18/2008), Chih-Hsiang Yang (07/18/2008), Sheng-Kai Hsu (07/18/2008), Yi-Chih Huang (07/21/2008), and Ying-Chao Chen (07/21/2008)

Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies)

Name: AU Optronics Corp.

Internal Address: \_\_\_\_\_

Street Address: \_\_\_\_\_

No. 1, Li-Hsin Road 2  
Science-Based Industrial Park

City: Hsin-Chu

State: \_\_\_\_\_

Country: Taiwan, R.O.C. Zip: \_\_\_\_\_

Additional name(s) & address(es) attached?  Yes  No

3. Nature of conveyance/Execution Date(s):

Execution Date(s): in parentheses after inventor name

Assignment  Merger  Change of Name

Security Agreement  Joint Research Agreement

Government Interest Assignment

Executive Order 9424, Confirmatory License

Other \_\_\_\_\_

4. Application or patent number(s):

This document is being filed together with a new application.

A. Patent Application No.(s)

CHIP ON FILM STRUCTURE

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Robert H. Berdo, Jr.  
RABIN & BERDO, PC

Internal Address: Atty. Dkt.: TSAI-394

Street Address: 1101 14th St., NW  
Suite 500

City: Washington

State: DC Zip: 20005

Phone Number: (202) 371-8976

Fax Number: (202) 408-0924

Email Address: firm@rabinberdo.com

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers 5730  
Expiration Date 04/11

b. Deposit Account Number \_\_\_\_\_  
Authorized User Name \_\_\_\_\_

08/08/2008 MAHNE1 00000058 1222354

04 FC:0021

AB 08 OP

9. Signature:

*Robert H. Berdo, Jr.*

Signature

August 7, 2008  
Date

Robert H. Berdo, Jr. - 38,075  
Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

9

FEE ENCLOSED: \$ 40.00  
Please charge any further fee to our Deposit Account No. 18-0002

## ASSIGNMENT

This assignment agreement is applicable to an invention entitled (Invention Title) \_\_\_\_\_  
CHIP ON FILM STRUCTURE

The PATENT RIGHTS referred to in this agreement are:

(check one)  a patent application for this invention, executed by the ASSIGNOR(S)  
 concurrently with this assignment.

U.S. patent application Serial No. \_\_\_\_\_, filed \_\_\_\_\_

a U.S. patent application based on PCT International Application  
 No. \_\_\_\_\_ filed on (date) \_\_\_\_\_ (U.S. patent application  
 Serial No. \_\_\_\_\_, if known).

U.S. patent No. \_\_\_\_\_, issued \_\_\_\_\_.

The PATENT RIGHTS also include all divisions reissues, continuations and extensions of  
 the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

(check one)  U.S. patent rights only.

Worldwide patent rights. In this case, the assignee shall have the right to  
 claim the benefit of the filing date of any U.S. or foreign patent application  
 for this invention.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures  
 appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) AU Optronics Corporation

(Address) NO. 1, LI-HSIN ROAD 2, SCIENCE-BASED INDUSTRIAL PARK,  
 HSIN-CHU, TAIWAN, R.O.C.

The ASSIGNEE is:

(check one)  An individual.

A Partnership.

A Corporation of TAIWAN, R.O.C. (specify state or country)

(other) \_\_\_\_\_

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and  
 valuable consideration, receipt of which is acknowledged, hereby assign(s) the following  
 rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable  
 provisions, based on any earlier patent applications for this invention.

THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO  
ASSIGNEE: AU Optronics Corporation  
INVENTION TITLE: CHIP ON FILM STRUCTURE

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

Ke-Chih CHANG

Name of sole or first inventor

Ke-chih CHANG

Signature

July 18, 2008

Date

Chih-Hsiang YANG

Name of second inventor, if any

Chih-Hsiang YANG

Signature

July 18, 2008

Date

Sheng-Kai HSU

Name of third inventor, if any

Signature

Date

Yi-Chih HUANG

Name of fourth inventor, if any

Signature

Date

Ying-Chao CHEN

Name of fifth inventor, if any

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Name of sixth inventor, if any

Signature

Date

Name of seventh inventor, if any

Signature

Date

Name of eighth inventor, if any

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Name of third inventor, if any

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Yi-Chih HUANG

Name of fourth inventor, if any

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Ying-Chao CHEN

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Yi-Chih HUANG

Name of fourth inventor, if any

Signature

Date

*Yi-Chih Huang*

*July 20th / 2008*

Ying-Chao CHEN

Name of fifth inventor, if any

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Name of sixth inventor, if any

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Ying-Chao CHEN

Name of fifth inventor, if any

Signature

Date

July 21, 2008

Name of sixth inventor, if any

Signature

Date

Name of seventh inventor, if any

Signature

Date

Name of eighth inventor, if any

Signature

Date